NOTES:
1. DIE ROTATION IS WITHIN +/- 1 DEGREE
2. NO MATERIALS OVERHANG PAST THE OUTER EDGES OF THE CERAMIC PACKAGE.
1. CENTER OF ACTIVE IMAGE ARRAY IS AT CENTER OF DIE.

2. DIE IS CENTERED AND AlIGNED WITHIN OUTER EDGES OF THE CERAMIC PACKAGE.

NOTES:

SHOWN WITHOUT COVER GLASS

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